

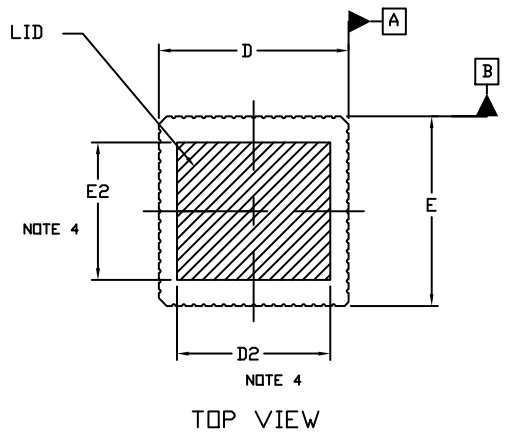
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



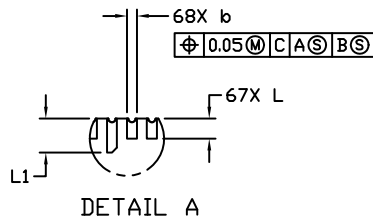
LCC68, 24.13x24.13 CASE 115AQ ISSUE A

DATE 01 DEC 2011

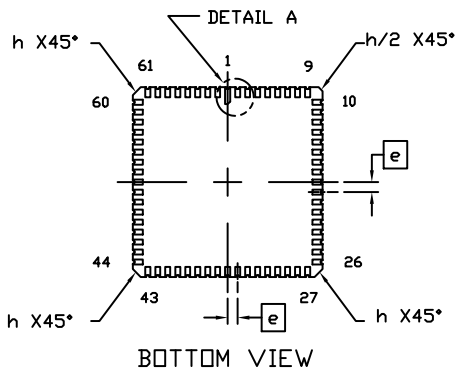
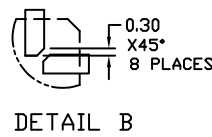
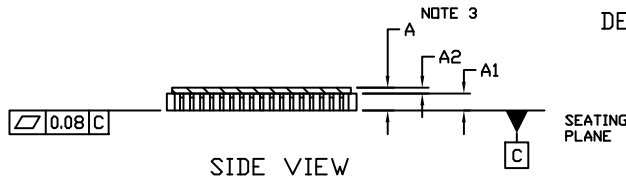


NOTES:

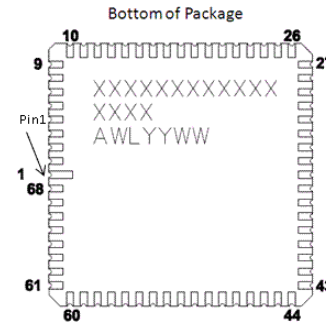
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. THE LID DEFINED BY DIMENSIONS D2 AND E2 MUST BE LOCATED WITHIN DIMENSIONS D AND E.



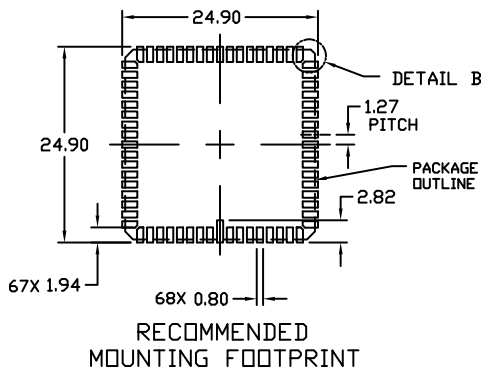
DIM	MILLIMETERS	
	MIN.	MAX.
A	2.98	4.10
A1	3.05	REF
A2	0.49	REF
b	0.50	0.77
D	23.88	24.51
D2	19.50	REF
E	23.88	24.51
E2	17.50	REF
e	1.27	BSC
h	1.02	REF
L	1.07	1.47
L1	1.91	2.41



GENERIC MARKING DIAGRAM



XXXXX = Specific Device Code
 A = Assembly Location
 WL = Wafer Lot
 YY = Year
 WW = Work Week
 NNNN = Serial Number



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DESCRIPTION:	LCC68, 24.13 X 24.13	PAGE 1 OF 1

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